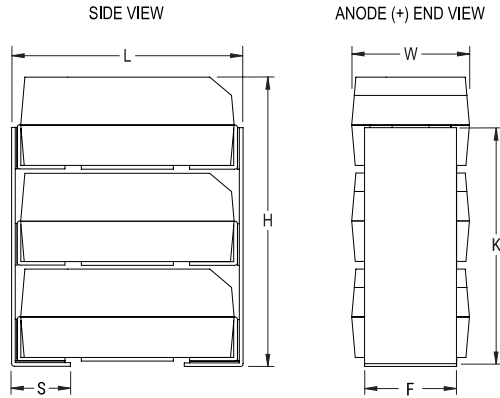



TSP, Tantalum, Polymer Tantalum, HRA, 990 uF, 20%, 6.3 VDC, 3D



Dimensions	
Case Code	3D
L	8mm +/-0.38mm
W	4.4mm +/-0.2mm
H	9.2mm +/-0.38mm
S	1.9mm +/-0.38mm
F	3mm +/-0.2mm
K	7.7mm +/-0.38mm

Packaging Specifications	
Packaging:	Tray
Packaging Quantity:	50

General Information	
Series:	TSP
Dielectric:	Polymer Tantalum
Style:	Stacked Chip
Description:	SMD, Polymer, KO, Stacks, High Reliability
Features:	High Reliability
RoHS:	No
Prop 65:	 WARNING: Cancer and reproductive harm - www.p65warnings.ca.gov
SCIP Number:	30e82d35-b509-48ec-8c77-2d5ec01b3abc
Termination:	Solder Coated
Termination (Stack):	Silver Plated
AEC-Q200:	No
MSL:	3

Specifications	
Capacitance:	990 uF
Capacitance Tolerance:	20%
Voltage DC:	6.3 VDC (105C), 4.22 VDC (125C)
Temperature Range:	-55/+125°C
Rated Temperature:	105°C
Dissipation Factor:	10% 120Hz 25C
Failure Rate:	N/A
Resistance:	14 mOhms (100kHz 25C)
Leakage Current:	624 uA (5min 25°C)
Testing and Reliability:	10 Cycles Surge Current Testing At -55C And +85C

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

单击下面可查看定价，库存，交付和生命周期等信息

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